

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## WAFER SPACE SUPPORTING APPARATUS INSTALLED ON ELECTROSTATIC CHUCK AND METHOD FOR FABRICATING SAME

was filed on and w	as United States A	Application Number or PCT International if applicable).	l Application Number	
I hereby state that I have reviewed and amendment referred to above.	understand the contents of the above-ident	tified specification, including the claims	, as amended by any	
I acknowledge the duty to disclose info Regulations § 1.56.	rmation which is known by me to be mate	erial to patentability as defined in Title	37, Code of Federal	
inventor's certificate, or § 365(a) of any Po		ed at least one country other than the Unite	le 37, Code of Federal	
NUMBER	COUNTRY	DAY/MONTH/YEAR FILED		
2001-29656	Republic of Korea	29/May/2001	Yes	
I hereby claim the benefit under Title 35, I	United States Code § 119(e) of any United St	tates provisional application(s) listed belo	w.	
APPLICAT	TON NO.	FILING DATE		
			119	

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is known by me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

PAGE 2

Docket No\_249/115

APPLICATION SERIAL NO.	FILING DATE		NTED, PENDING. DONED
·			
dress all correspondence to Eugene M. Lee, The L Ol. Address all telephone communications to Eug	aw Offices of Eugene M. Lee, PLLC, 21: ene M. Lee at (703) 525-0978.	a, Reg. No. 43,162.	200, Arlington, V
ereby appoint as my attorneys, with full powers of d Trademark Office connected therewith: Eugene M dress all correspondence to Eugene M. Lee, The L 201. Address all telephone communications to Eugereby declare that all statements made herein of my true; and further that these statements were made prisonment, or both, under Section 1001 of Title 18 application or any patent issued thereon.	aw Offices of Eugene M. Lee, PLLC, 21: ene M. Lee at (703) 525-0978.  own knowledge are true and that all state with the knowledge that willful false state 3 of the United States Code and that such	a, Reg. No. 43,162.  If Wilson Boulevard, Suite 1  ments made on information a ments and the like so made a willful false statements may j	200, Arlington, V and belief are belie are punishable by icopardize the vali
dress all correspondence to Eugene M. Lee, The I 201. Address all telephone communications to Eugene by declare that all statements made herein of my true; and further that these statements were made prisonment, or both, under Section 1001 of Title 18 application or any patent issued thereon.	aw Offices of Eugene M. Lee. PLLC, 21: ene M. Lee at (703) 525-0978.  own knowledge are true and that all state with the knowledge that willful false state 3 of the United States Code and that such  Signature of	a, Reg. No. 43,162.  If Wilson Boulevard, Suite 1  ments made on information a	200, Arlington, V

Post Office Address
Same as above